

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
PEDRO CHINNI	04/27/2014
FRANCISCO SAHLI	04/27/2014
RECEIVING PARTY DATA	
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State/Country:	CHILE
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	14639370
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DATE SIGNED:	11/04/2016
Total Attachments: 1	
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Cesión

Conste que el/los abajo firmante(s)

inventor de una invención relativa a:

Solicitud internacional N°:

Fecha de Solicitud:

por el presente la(s) cede(n), y transfiere(n) en toda su propiedad y dominio a

WENCO S.A.

domiciliados en

Américo Vespucio Norte, 1125, Huechuraba, Santiago, Chile

a quien(es) ha(n) cedido todos sus derechos a la Invención arriba citada, comprendiéndose los derechos de prioridad, los Certificados de Registro otorgado, y en relación con todas y cada una de las nuevas solicitudes, nuevas presentaciones, divisionales, substituciones o extensiones de dicha solicitud en cuanto se refiere al territorio de

sin restricción de ninguna clase.

Dado y firmado en _____

Assignment

Be it known that I/we the undersigned

inventor of an invention related to:

Light and integrated junction system of the walls of a collapsible container

International Application No.:

CL 00879-2014

Application date:

Filed before the Chilean Patent and Trademark Office on April 8th, 2014

do hereby assign, and transfer all my/our rights, title and interest in and to the same to

WENCO S.A.

residing in

Américo Vespucio Norte, 1125, Huechuraba, Santiago, Chile

to whom assignment has been made of all rights and title to the said invention, including priority rights, the Letters Patent related to such Patent Application, including each and every Letters Patent granted, new applications, new filings and regarding each and every reissue, refilling, divisional, substitution or extension of said Patent Application for the territory of

the aforesaid without any restriction whatever.

Done and signed at *Santiago, Chile on April 27th, 2014*

Firma de los Cesionarios/Signature of Assignor(s)

Franco Salm

Peoro Chinn